



/ Revised record

E	2' (8-4				
F	2' (9-4-3	(			
G	2' 2' -(-3		RDSON 25mR	SX	



**/ Descriptions**

ZR[ L3(2' SE / ZR[ L3(2' SE z  
 { | } ~ € OSFE, f „ ...† ‡ ^ %Š ‡  
 ZR[ L3(2' SE < Œ Œ' Œ' " ‡" • • - — ~ ™Š > œŠ Ÿ j ç é  
 ¨ ¥ | § " © - — ª « Š - - ® - ° | ±

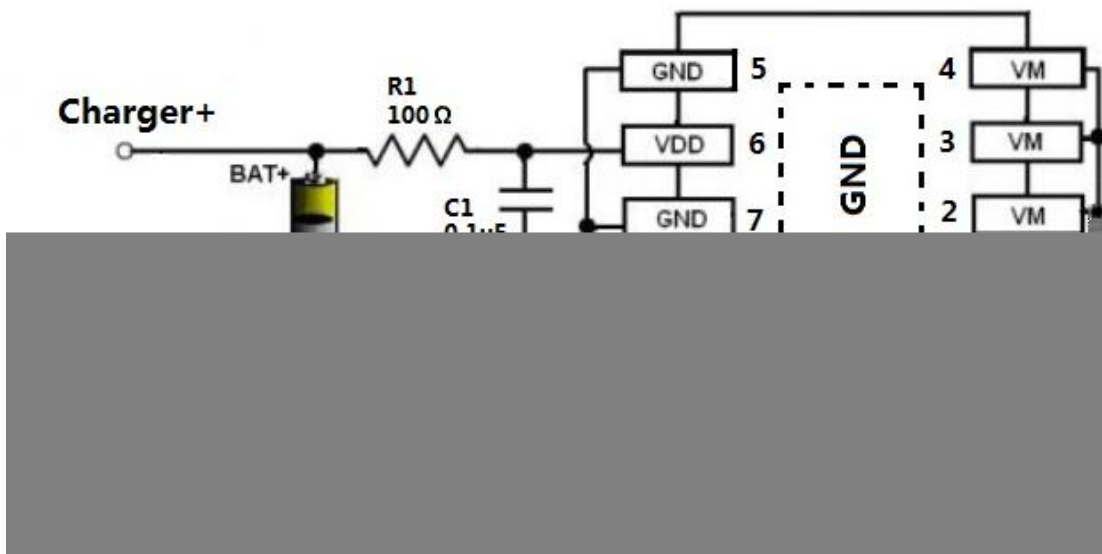
**/ Features**

- ◆ 2 " 3 25m' | } ~ € OSFE, μ
- ◆ 1. ‡, μ
- ◆ Œ' μ Œ' μ 2° Œ' » Œ' ' ¼½" ‡ ' μ
- ◆ ¾...† μ' ¿ ~ %Š Š - ² Á Â f „ ...† μ
- ◆ ç Æ Æ ' » Ä j > œ ' » 5ÆÉμ Ê Ê ' » 3ÆÉì í ROÍ S ^ Ì Ð Ñ
- ◆

**/ Applications**

μ

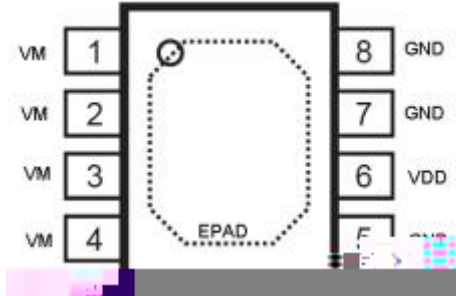
**/ Typical Application**



Ò Ó » ( Æ Ó Ô Õ Ö Ò „ ^ ¼½ ' × Ø Ù ¨ Ú Û Ü Ý • Þ ß à á  
 ² Æ < â ã ~ ä Ú — Û Ü à á Þ ß Ä ~ ä



**/ Pinning**



Pin	Label	Dimensions
1, 2, 3, 4	VM	3/4" x 1/4" x 1/2" x 1/4"
5, 8	GND	1/4"
6	VDD	1/4"
9	EPAD	EPAD

**/ Marking**

See Marking Instructions.



ü ý	þ ý	ý	
¿ DDô ë ÔÕ „	V <sub>IN</sub>	-0.3 to +6.0	V
¿ € ô ë ÔÕ „	V <sub>VM</sub>	-6.0 to +10	V
à á <sup>1</sup>	T <sub>J</sub>	125	
ö <sup>1</sup>	T <sub>L</sub>	300	°C
> œ <sup>1</sup>	T <sub>opr</sub>	-40 to +85	°C
<sup>1</sup>	T <sub>stg</sub>	-55 to +150	°C
ã Ä	ESD	2000	V

ü ý	þ ý	†	à		à á	
œ ...† „	V <sub>CU</sub>		4.25	4.30	4.35	V
œ ' „	V <sub>CL</sub>		4.05	4.10	4.15	V
œ' ...† „	V <sub>DL</sub>		2.30	2.40	2.50	V
œ' ' „	V <sub>DR</sub>		2.90	3.00	3.10	V
<sup>3/4</sup> ...† „	V <sub>CHA</sub>			-0.12		V

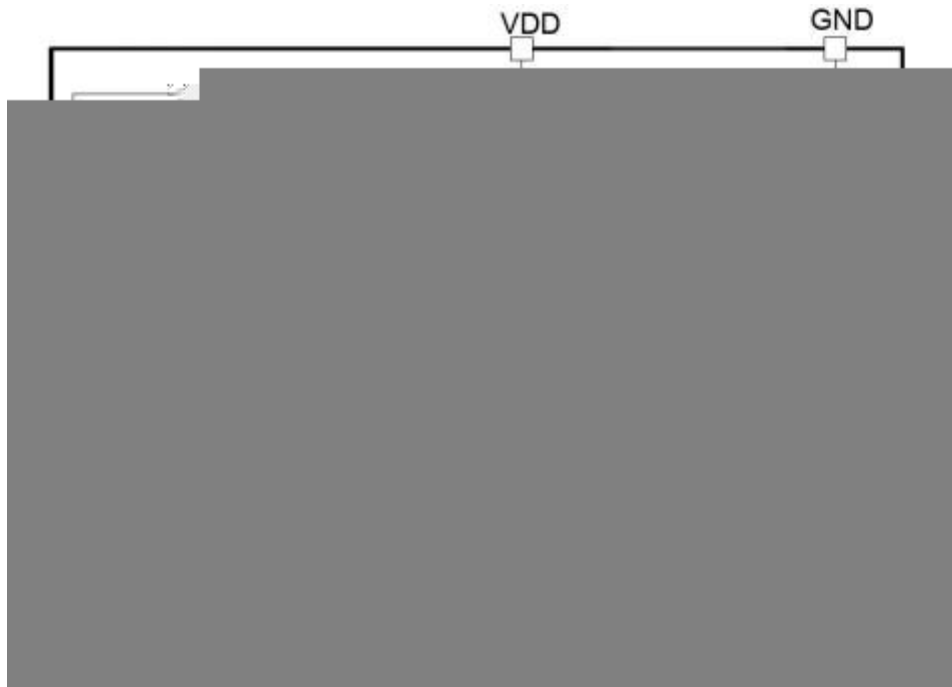
œ' ' ...† (

I<sub>IOV1</sub>

V<sub>dd</sub>=3.5V

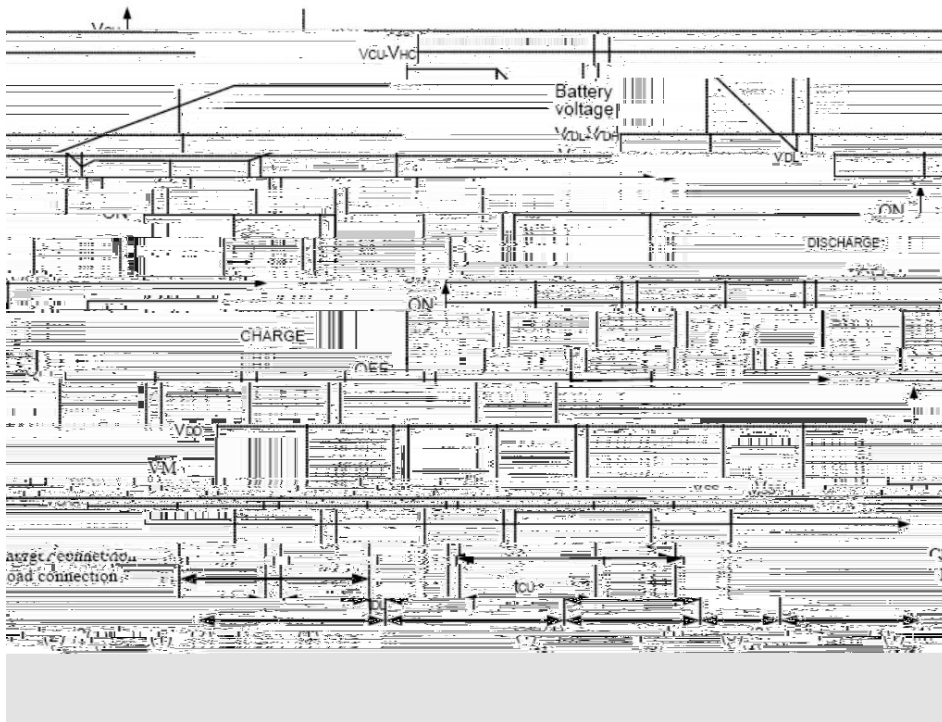
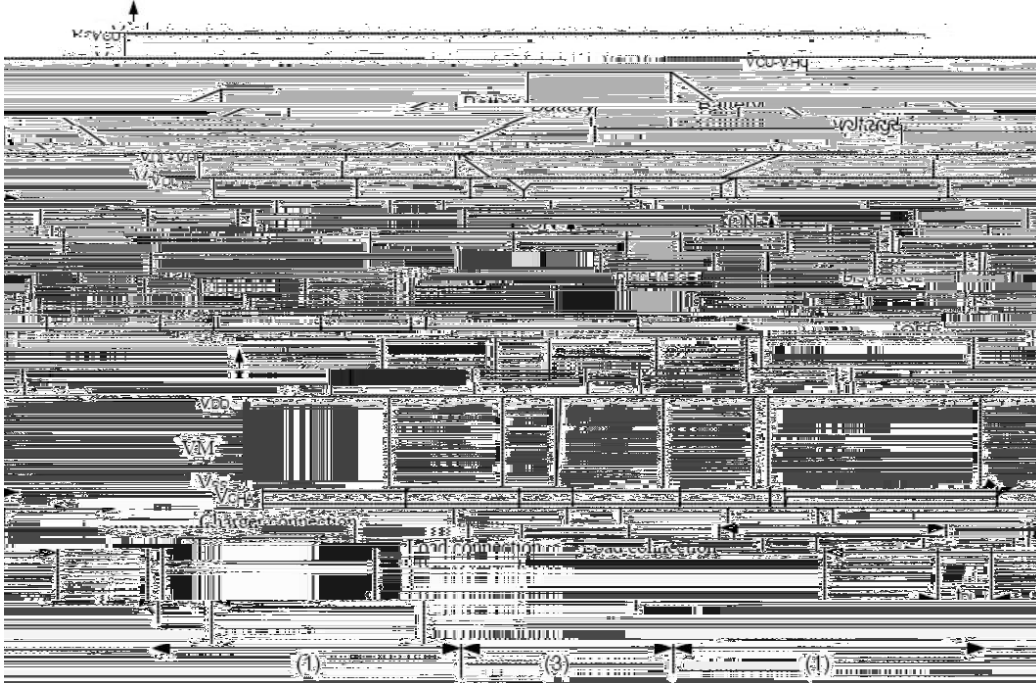
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A









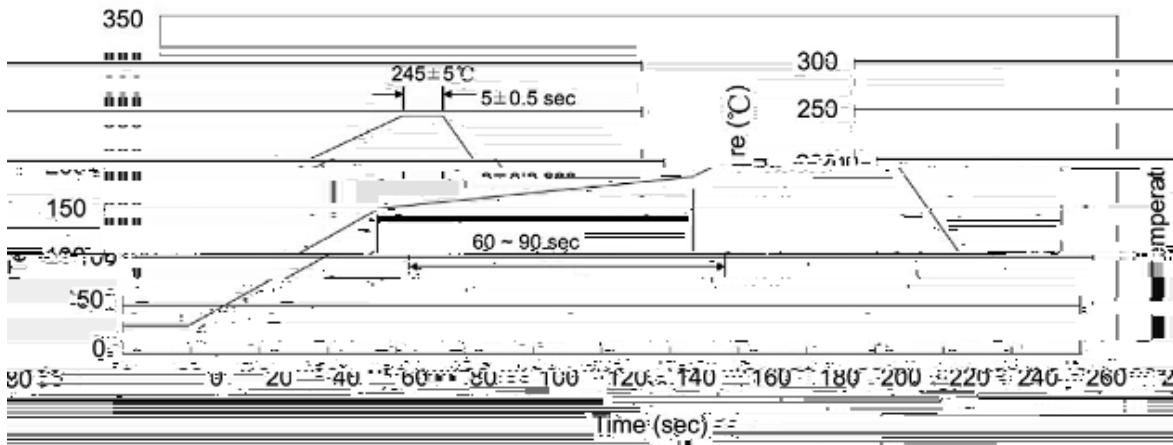
1 2 3 4







( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- |   |       |     |       |          |   |
|---|-------|-----|-------|----------|---|
| 1 | 150   | 180 | 60    | 90sec;   | 1.Preheating:150~180 , Time:60~90sec.   |
| 2 | 245±5 |     | 5±0.5 | sec;     | 2.Peak Temp.:245±5 , Duration:5±0.5sec. |
| 3 |       |     | 2     | 10 /sec. | 3. Cooling Speed: 2~10 /sec.            |

/ Resistance to Soldering Heat Test Conditions

260±5 B